### 3.5x2.8mm SURFACE MOUNT LED LAMP



#### **ATTENTION**

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES** 

Part Number: AAAF3529LSEKJ3ZGKQBS

Hyper Red Green Blue

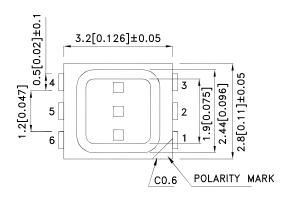
#### **Features**

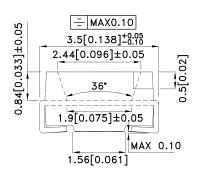
- Outstanding material efficiency.
- Low power consumption.
- Can produce any color in visible spectrum, including white light.
- Suitable for all SMD assembly and solder process.
- Available on tape and reel.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- RoHS compliant.

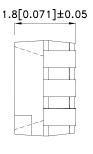
### **Descriptions**

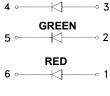
- The Hyper Red device is based on light emitting diode chip made from AlGaInP.
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- The Blue source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

## **Package Dimensions**

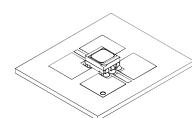








**BLUE** 



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

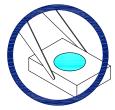
  4. The device has a single mounting surface. The device must be mounted according to the specifications.

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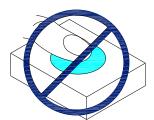
### **Handling Precautions**

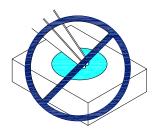
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly Orangeuces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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### **Selection Guide**

Part No.	Emitting Color (Material)	Lens Type	Iv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Тур.	201/2
AAAF3529LSEKJ3ZGKQBS	Hyper Red (AlGaInP)		30	60	120°
	Green (InGaN)	Water Clear	80	180	
	Blue (InGaN)		12	30	

#### Notes:

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity / luminous Flux: +/-15%.
- 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green Blue	640 515 460		nm	IF=2mA
λD [1]	Dominant Wavelength	Hyper Red Green Blue	625 525 465		nm	IF=2mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green Blue	20 35 25		nm	IF=2mA
С	Capacitance	Hyper Red Green Blue	27 45 100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green Blue	1.8 2.65 2.65	2.1 3.1 3.1	V	IF=2mA
lR	Reverse Current	Hyper Red Green Blue		10 50 50	uA	V <sub>R</sub> =5V

#### Notes:

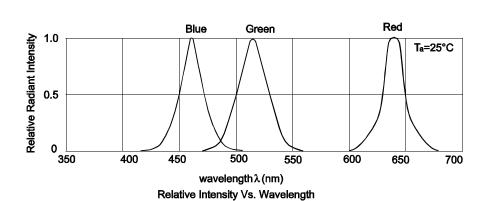
- 1.Wavelength: +/-1nm.
- 2.Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4.Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

### Absolute Maximum Ratings at TA=25°C

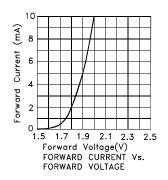
Parameter	Hyper Red	Green	Blue	Units		
Power dissipation	105	93	93	mW		
DC Forward Current	50	30	30	mA		
Peak Forward Current [1]	150	150	150	mA		
Electrostatic Discharge Threshold (HBM)	3000	450	250	V		
Reverse Voltage	5		V			
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

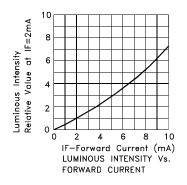
Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

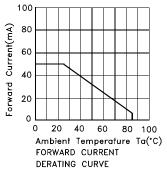
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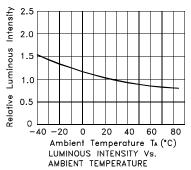


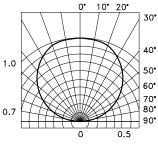
# AAAF3529LSEKJ3ZGKQBS Hyper Red









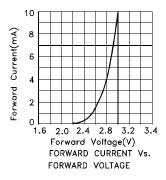


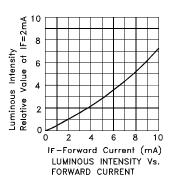
SPATIAL DISTRIBUTION

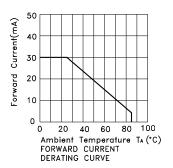
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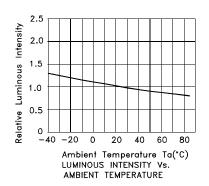
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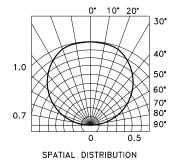
## Green







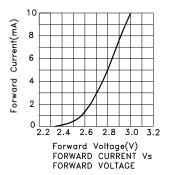


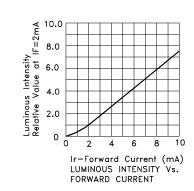


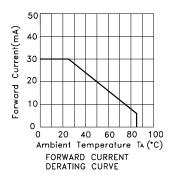
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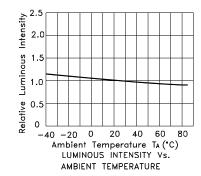
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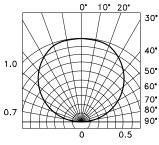
## Blue











SPATIAL DISTRIBUTION

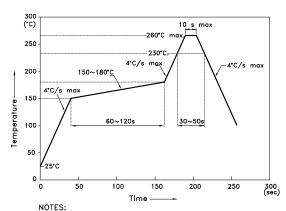
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### AAAF3529LSEKJ3ZGKQBS

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



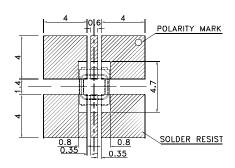
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

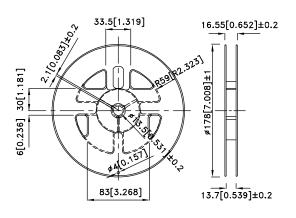
  3.Number of reflow process shall be 2 times or less.

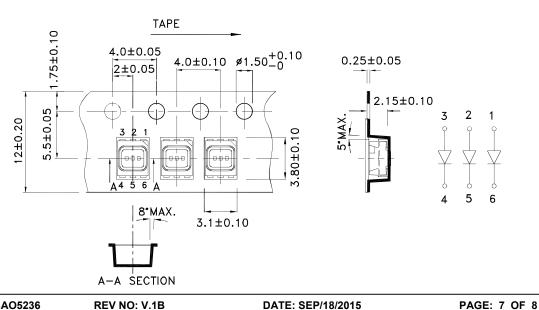
# **Recommended Soldering Pattern** (Units: mm; Tolerance: ± 0.1)



**Tape Dimensions** (Units : mm)

### **Reel Dimension**





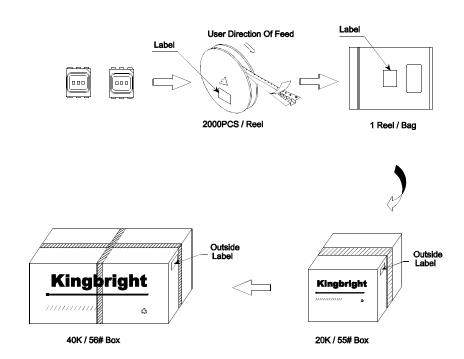
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#### **PACKING & LABEL SPECIFICATIONS**

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